

M5M5V216AWG

2097152-BIT (131072-WORD BY 16-BIT) CMOS STATIC RAM

DESCRIPTION

The M5M5V216A is a family of low voltage 2-Mbit static RAMs organized as 131,072-words by 16-bit, fabricated by Mitsubishi's high-performance 0.25μm CMOS technology.

The M5M5V216A is suitable for memory applications where a simple interfacing, battery operating and battery backup are the important design objectives.

M5M5V216AWG is packaged in a CSP (chip scale package), with the outline of 7.0mm x 8.5mm, ball matrix of 6 x 8 (48pin) and ball pitch of 0.75mm. It gives the best solution for a compaction of mounting area as well as flexibility of wiring pattern of printed circuit boards.

From the point of operating temperature, the family is divided into three versions; "Standard", "W-version", and "I-version". Those are summarized in the part name table below.

FEATURES

- Single +2.7~+3.6V power supply
- Small stand-by current: 0.3μA(3V,typ.)
- No clocks, No refresh
- Data retention supply voltage=2.0V to 3.6V
- All inputs and outputs are TTL compatible.
- Easy memory expansion by \bar{S} , BC1 and BC2
- Common Data I/O
- Three-state outputs: OR-tie capability
- OE prevents data contention in the I/O bus
- Process technology: 0.25μm CMOS
- Package: 48 pin 7.0mm x8.5mm CSP

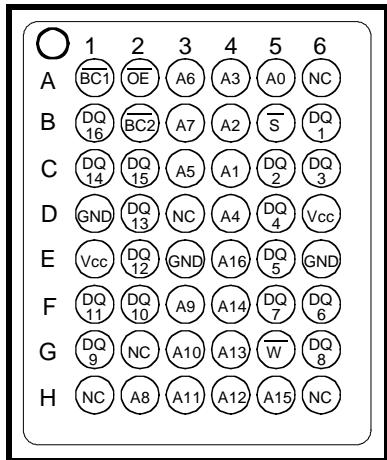
PART NAME TABLE

Version, Operating temperature	Part name	Power Supply	Access time max.	Stand-by current Icc(PD), Vcc=3.0V						Active current Icc1 (3.0V, typ.)	
				typical *		Ratings (max.)					
				25°C	40°C	25°C	40°C	70°C	85°C		
Standard 0 ~ +70°C	M5M5V216AWG -55L	2.7 ~ 3.6V	55ns(@ 2.7V) / 50ns(@3.3V)	0.3μA	---	---	---	20μA	---	45mA (10MHz)	
	M5M5V216AWG -70L		70ns(@ 2.7V) / 65ns(@3.3V)		---	---	---	---	---		
	M5M5V216AWG -55H	2.7 ~ 3.6V	55ns(@ 2.7V) / 50ns(@3.3V)		1μA	1μA	3μA	8μA	---		
	M5M5V216AWG -70H		70ns(@ 2.7V) / 65ns(@3.3V)		---	---	---	---	---		
W-version -20 ~ +85°C	M5M5V216AWG -55LW	2.7 ~ 3.6V	55ns(@ 2.7V) / 50ns(@3.3V)	0.3μA	---	---	---	20μA	50μA	5mA (1MHz)	
	M5M5V216AWG -70LW		70ns(@ 2.7V) / 65ns(@3.3V)		---	---	---	---	---		
	M5M5V216AWG -55HW	2.7 ~ 3.6V	55ns(@ 2.7V) / 50ns(@3.3V)		1μA	1μA	3μA	8μA	24μA		
	M5M5V216AWG -70HW		70ns(@ 2.7V) / 65ns(@3.3V)		---	---	---	---	---		
I-version -40 ~ +85°C	M5M5V216AWG -55LI	2.7 ~ 3.6V	55ns(@ 2.7V) / 50ns(@3.3V)	0.3μA	---	---	---	20μA	50μA	5mA (1MHz)	
	M5M5V216AWG -70LI		70ns(@ 2.7V) / 65ns(@3.3V)		---	---	---	---	---		
	M5M5V216AWG -55HI	2.7 ~ 3.6V	55ns(@ 2.7V) / 50ns(@3.3V)		1μA	1μA	3μA	8μA	24μA		
	M5M5V216AWG -70HI		70ns(@ 2.7V) / 65ns(@3.3V)		---	---	---	---	---		

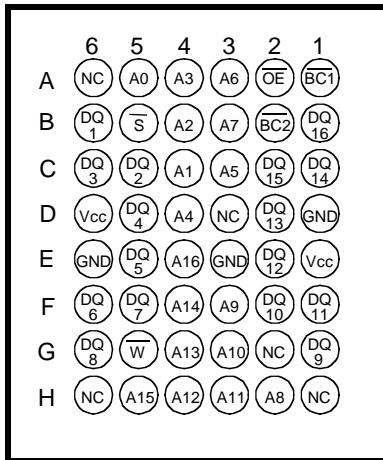
* "typical" parameter is sampled, not 100% tested.

PIN CONFIGURATION

(TOP VIEW)



(BOTTOM VIEW)



Pin	Function
A0 ~ A16	Address input
DQ1 ~ DQ16	Data input / output
\bar{S}	Chip select input
\bar{W}	Write control input
OE	Output inable input
$\bar{BC1}$	Lower Byte (DQ1 ~ 8)
$\bar{BC2}$	Upper Byte (DQ9 ~ 16)
Vcc	Power supply
GND	Ground supply

Outline: 48FJA

NC: No Connection



MITSUBISHI ELECTRIC

M5M5V216AWG

2097152-BIT (131072-WORD BY 16-BIT) CMOS STATIC RAM

FUNCTION

The M5M5V216AWG is organized as 131,072-words by 16-bit. These devices operate on a single +2.7~3.6V power supply, and are directly TTL compatible to both input and output. Its fully static circuit needs no clocks and no refresh, and makes it useful.

The operation mode are determined by a combination of the device control inputs $\overline{BC1}$, $\overline{BC2}$, \overline{S} , \overline{W} and \overline{OE} . Each mode is summarized in the function table.

A write operation is executed whenever the low level \overline{W} overlaps with the low level $\overline{BC1}$ and/or $\overline{BC2}$ and the low level \overline{S} . The address(A0~A16) must be set up before the write cycle and must be stable during the entire cycle.

A read operation is executed by setting \overline{W} at a high level and \overline{OE} at a low level while $\overline{BC1}$ and/or $\overline{BC2}$ and \overline{S} are in an active state($S=L$).

When setting $\overline{BC1}$ at the high level and other pins are in an active stage , upper-byte are in a selectable mode in which both reading and writing are enabled, and lower-byte are in a non-selectable mode. And when setting $\overline{BC2}$ at a high level and other pins are in an active stage, lower-byte are in a selectable mode and upper-byte are in a non-selectable mode.

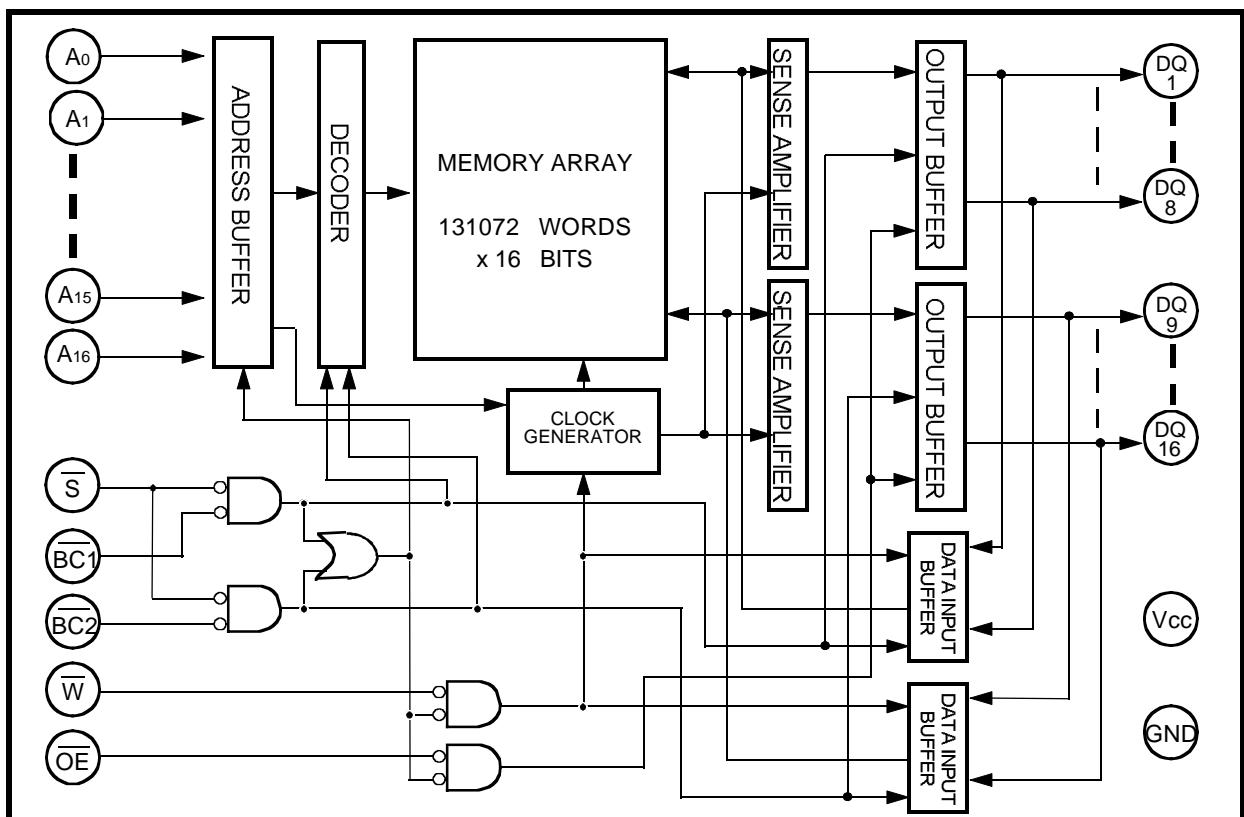
When setting $\overline{BC1}$ and $\overline{BC2}$ at a high level or \overline{S} at a high level, the chips are in a non-selectable mode in which both reading and writing are disabled. In this mode, the output stage is in a high-impedance state, allowing OR-tie with other chips and memory expansion by $\overline{BC1}$, $\overline{BC2}$ and \overline{S} .

The power supply current is reduced as low as 0.3 μ A(25°C, typical), and the memory data can be held at +2V power supply, enabling battery back-up operation during power failure or power-down operation in the non-selected mode.

FUNCTION TABLE

\overline{S}	$\overline{BC1}$	$\overline{BC2}$	\overline{W}	\overline{OE}	Mode	DQ1~8	DQ9~16	Icc
H	X	X	X	X	Non selection	High-Z	High-Z	Standby
L	H	H	X	X	Non selection	High-Z	High-Z	Standby
L	L	H	L	X	Write	Din	High-Z	Active
L	L	H	H	L	Read	Dout	High-Z	Active
L	L	H	H	H	—	High-Z	High-Z	Active
L	H	L	L	X	Write	High-Z	Din	Active
L	H	L	H	L	Read	High-Z	Dout	Active
L	H	L	H	H	—	High-Z	High-Z	Active
L	L	L	X	X	Write	Din	Din	Active
L	L	L	H	L	Read	Dout	Dout	Active
L	L	L	H	H	—	High-Z	High-Z	Active

BLOCK DIAGRAM



M5M5V216AWG**2097152-BIT (131072-WORD BY 16-BIT) CMOS STATIC RAM****ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Conditions	Ratings	Units
V_{CC}	Supply voltage	With respect to GND	-0.5* ~ +4.6	V
V_I	Input voltage	With respect to GND	-0.5* ~ $V_{CC} + 0.5$	
V_O	Output voltage	With respect to GND	0 ~ V_{CC}	
P_d	Power dissipation	$T_a=25^\circ C$	700	mW
T_a	Operating temperature	Standard (-L, -H)	0 ~ +70	$^\circ C$
		W-version (-LW, -HW)	-20 ~ +85	
		I-version (-LI, -HI)	-40 ~ +85	
T_{STG}	Storage temperature		-65 ~ +150	$^\circ C$

* -3.0V in case of AC (Pulse width $\leq 30\text{ns}$)**DC ELECTRICAL CHARACTERISTICS**($V_{CC}=2.7 \sim 3.6V$, unless otherwise noted)

Symbol	Parameter	Conditions	Limits			Units
			Min	Typ	Max	
V_{IH}	High-level input voltage		2.0		$V_{CC}+0.3V$	V
V_{IL}	Low-level input voltage		-0.3 *		0.6	
V_{OH1}	High-level output voltage 1	$I_{OH} = -0.5\text{mA}$	2.4			
V_{OH2}	High-level output voltage 2	$I_{OH} = -0.05\text{mA}$	$V_{CC}-0.5V$			
V_{OL}	Low-level output voltage	$I_{OL} = 2\text{mA}$			0.4	
I_I	Input leakage current	$V_I = 0 \sim V_{CC}$			± 1	μA
I_o	Output leakage current	$\overline{BC1} \text{ and } \overline{BC2} = V_{IH} \text{ or } \overline{S} = V_{IH} \text{ or } \overline{OE} = V_{IH}, V_{IO} = 0 \sim V_{CC}$			± 1	
I_{CC1}	Active supply current (AC,MOS level)	$\overline{BC1} \text{ and } \overline{BC2} \leq 0.2V, \overline{S} \leq 0.2V$ other inputs $\leq 0.2V$ or $\geq V_{CC}-0.2V$ Output - open (duty 100%)	$f = 10\text{MHz}$	-	45	60
			$f = 1\text{MHz}$	-	5	15
I_{CC2}	Active supply current (AC,TTL level)	$\overline{BC1} \text{ and } \overline{BC2} = V_{IL}, \overline{S} = V_{IL}$ other pins = V_{IH} or V_{IL} Output - open (duty 100%)	$f = 10\text{MHz}$	-	45	60
			$f = 1\text{MHz}$	-	5	15
I_{CC3}	Stand by supply current (AC,MOS level)	$\overline{BC1} \text{ and } \overline{BC2} \leq V_{CC} - 0.2V$ $\overline{S} \leq 0.2V$ Other inputs = $0 \sim V_{CC}$	$-LW, -LI$	$+70 \sim +85^\circ C$	-	60
			$-L, -LW, -LI$	$+70^\circ C$	-	20
			$-HW, -HI$	$+70 \sim +85^\circ C$	-	30
			$-H, -HW, -HI$	$+40 \sim +70^\circ C$	-	10
		$\overline{BC1} \text{ and } \overline{BC2} \geq V_{CC} - 0.2V$ $\overline{S} \leq 0.2V$ Other inputs = $0 \sim V_{CC}$	$+25 \sim +40^\circ C$	-	1	5
			$-H$	$0 \sim +25^\circ C$	-	2
			$-HW$	$-20 \sim +25^\circ C$	-	2
			$-HI$	$-40 \sim +25^\circ C$	-	2
I_{CC4}	Stand by supply current (AC,TTL level)	$\overline{BC1} \text{ and } \overline{BC2} = V_{IH}, \overline{S} = V_{IL}$ or $\overline{S} = V_{IH}$ Other inputs = $0 \sim V_{CC}$		-	-	0.5

Note 1: Direction for current flowing into IC is indicated as positive (no mark)

* -3.0V in case of AC (Pulse width $\leq 30\text{ns}$)Note 2: Typical value is for $V_{CC}=3.0V$ and $T_a=25^\circ C$ **CAPACITANCE**($V_{CC}=2.7 \sim 3.6V$, unless otherwise noted)

Symbol	Parameter	Conditions	Limits			Units
			Min	Typ	Max	
C_I	Input capacitance	$V_I = GND, V_I = 25\text{mVrms}, f = 1\text{MHz}$			8	pF
C_O	Output capacitance	$V_O = GND, V_O = 25\text{mVrms}, f = 1\text{MHz}$			10	

M5M5V216AWG

2097152-BIT (131072-WORD BY 16-BIT) CMOS STATIC RAM

AC ELECTRICAL CHARACTERISTICS (Vcc=2.7 ~ 3.6V, unless otherwise noted)

(1) TEST CONDITIONS

Supply voltage	2.7V~3.6V
Input pulse	$V_{IH}=2.2V, V_{IL}=0.4V$
Input rise time and fall time	5ns
Reference level	$V_{OH}=V_{OL}=1.5V$ Transition is measured $\pm 500mV$ from steady state voltage.(for t_{en}, t_{dis})
Output loads	Fig.1, CL=30pF CL=5pF (for t_{en}, t_{dis})

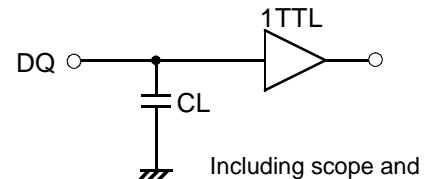


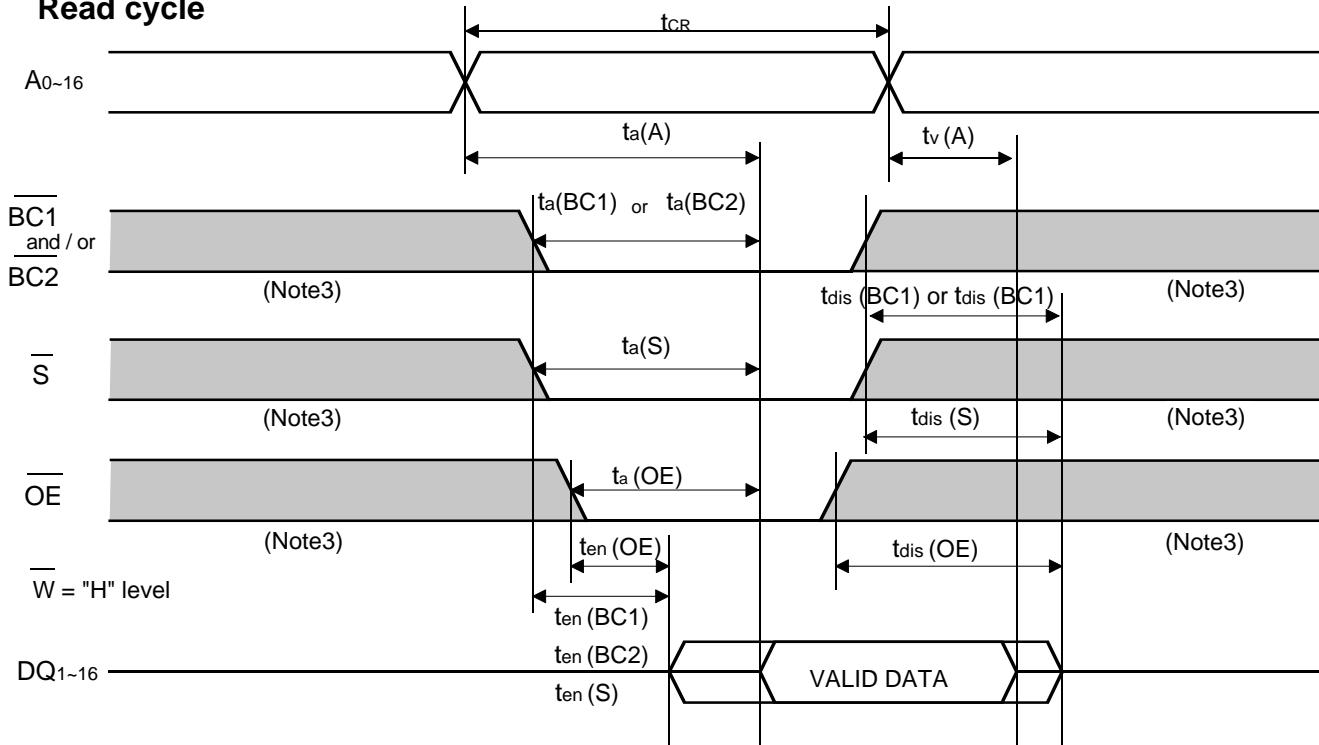
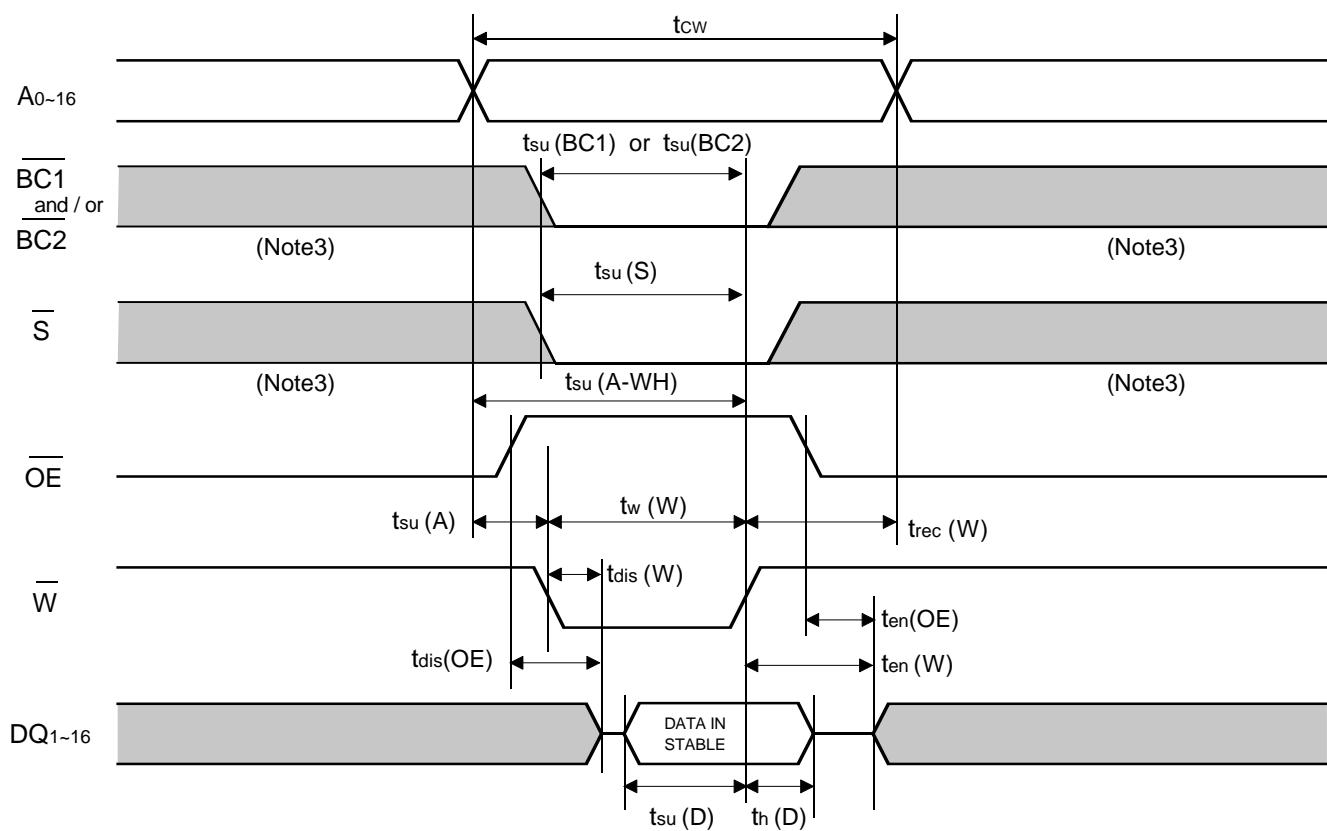
Fig.1 Output load

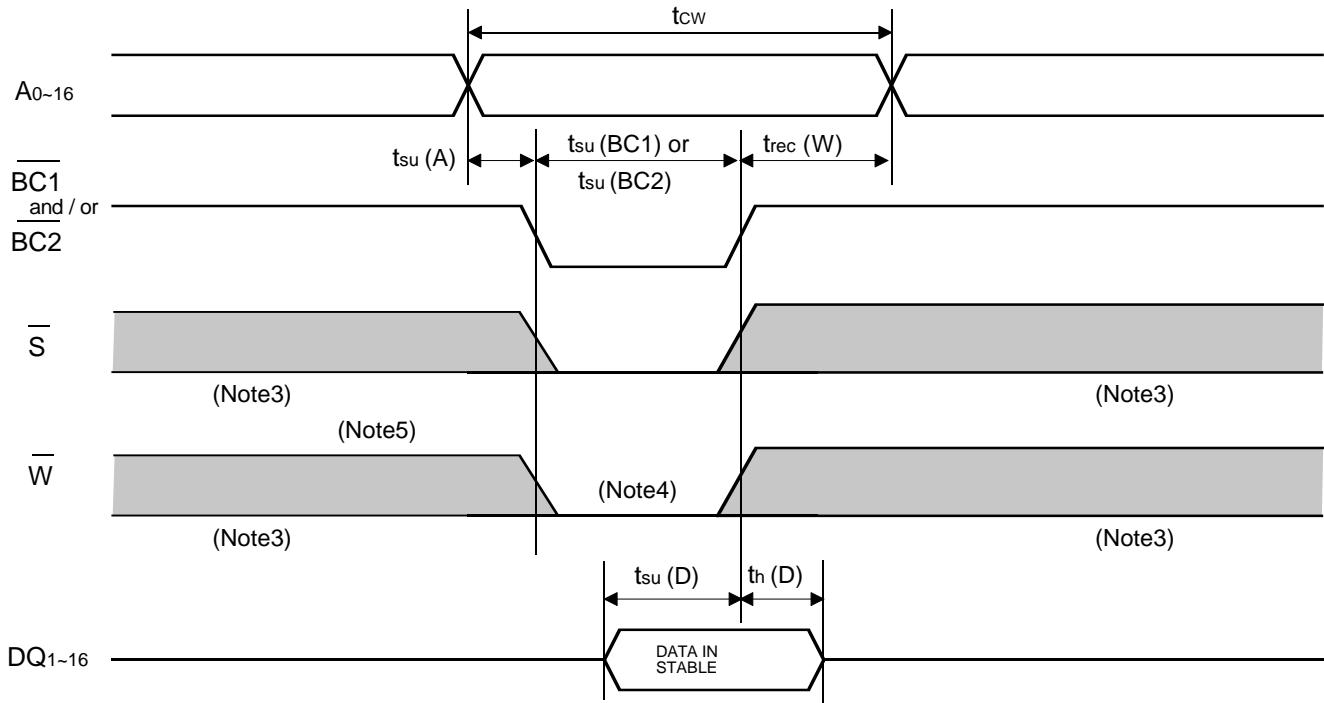
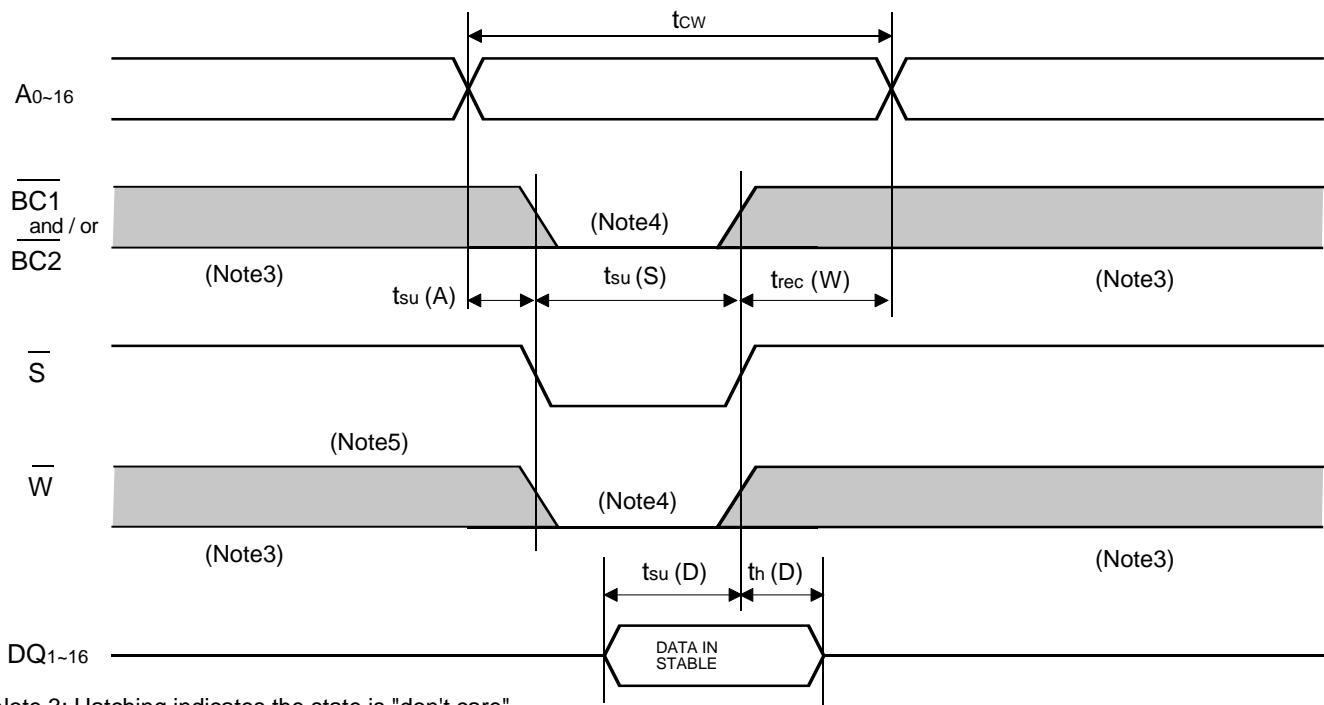
(2) READ CYCLE

Symbol	Parameter	Limits				Units	
		M5M5V216AWG - 55		M5M5V216AWG - 70			
		Min	Max	Min	Max		
t_{CR}	Read cycle time	55		70		ns	
$t_a(A)$	Address access time		55		70	ns	
$t_a(S)$	Chip select access time		55		70	ns	
$t_a(BC1)$	Byte control 1 access time		55		70	ns	
$t_a(BC2)$	Byte control 2 access time		55		70	ns	
$t_a(OE)$	Output enable access time		30		35	ns	
$t_{dis}(S)$	Output disable time after S high		20		25	ns	
$t_{dis}(BC1)$	Output disable time after BC1 high		20		25	ns	
$t_{dis}(BC2)$	Output disable time after BC2 high		20		25	ns	
$t_{dis}(OE)$	Output disable time after OE high		20		25	ns	
$t_{en}(S)$	Output enable time after S low	10		10		ns	
$t_{en}(BC1)$	Output enable time after BC1 low	10		10		ns	
$t_{en}(BC2)$	Output enable time after BC2 low	10		10		ns	
$t_{en}(OE)$	Output enable time after OE low	5		5		ns	
$t_v(A)$	Data valid time after address	10		10		ns	

(3) WRITE CYCLE

Symbol	Parameter	Limits				Units	
		M5M5V216AWG - 55		M5M5V216AWG - 70			
		Min	Max	Min	Max		
t_{cw}	Write cycle time	55		70		ns	
$t_w(W)$	Write pulse width	45		55		ns	
$t_{su}(A)$	Address setup time	0		0		ns	
$t_{su}(A-WH)$	Address setup time with respect to W	50		65		ns	
$t_{su}(BC1)$	Byte control 1 setup time	50		65		ns	
$t_{su}(BC2)$	Byte control 2 setup time	50		65		ns	
$t_{su}(S)$	Chip select setup time	50		65		ns	
$t_{su}(D)$	Data setup time	25		30		ns	
$t_h(D)$	Data hold time	0		0		ns	
$t_{rec}(W)$	Write recovery time	0		0		ns	
$t_{dis}(W)$	Output disable time from W low		20		25	ns	
$t_{dis}(OE)$	Output disable time from OE high		20		25	ns	
$t_{en}(W)$	Output enable time from W high	5		5		ns	
$t_{en}(OE)$	Output enable time from OE low	5		5		ns	

M5M5V216AWG**2097152-BIT (131072-WORD BY 16-BIT) CMOS STATIC RAM****(4)TIMING DIAGRAMS****Read cycle****Write cycle (W control mode)**

M5M5V216AWG**2097152-BIT (131072-WORD BY 16-BIT) CMOS STATIC RAM****Write cycle (BC control mode)****Write cycle (S control mode)**

Note 3: Hatching indicates the state is "don't care".

Note 4: A Write occurs during S low, overlaps BC1 and/or BC2 low and W low.

Note 5: When the falling edge of W is simultaneously or prior to the falling edge of BC1 and/or BC2 or the falling edge of S, the outputs are maintained in the high impedance state.

Note 6: Don't apply inverted phase signal externally when DQ pin is in output mode.



M5M5V216AWG

2097152-BIT (131072-WORD BY 16-BIT) CMOS STATIC RAM

POWER DOWN CHARACTERISTICS

(1) ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test conditions	Limits			Units		
			Min	Typ	Max			
Vcc (PD)	Power down supply voltage		2.0			V		
VI (BC)	Byte control input BC1 & BC2		2.0			V		
VI (\bar{S})	Chip select input \bar{S}		2.0			V		
Icc (PD)	Power down supply current	Vcc=3.0V 1) $\overline{BC1}$ and $\overline{BC2} \geq Vcc - 0.2V$ $\overline{S} \leq 0.2V$ other inputs=0~3V 2) $\overline{S} \geq Vcc - 0.2V$ other inputs=0~3V	-LW, -LI	+70 ~ +85°C	-	-	50	μA
			-L, -LW, -LI	+70°C	-	-	20	μA
			-HW, -HI	+70 ~ +85°C	-	-	24	μA
			-H, -HW, -HI	+40 ~ +70°C	-	-	8	μA
				+25 ~ +40°C	-	1	3	μA
			-H	0 ~ +25°C	-	0.3	1	μA
			-HW	-20 ~ +25°C	-	0.3	1	μA
			-HI	-40 ~ +25°C	-	0.3	1	μA

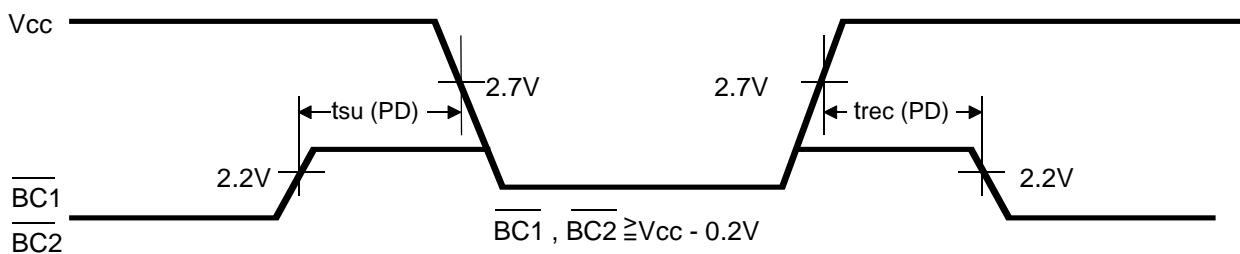
Typical value is for Ta=25°C

(2) TIMING REQUIREMENTS

Symbol	Parameter	Test conditions	Limits			Units
			Min	Typ	Max	
tsu (PD)	Power down set up time		0			ns
trec (PD)	Power down recovery time		5			ms

(3) TIMING DIAGRAM

BC control mode



S control mode

